

What is claimed is:

1. An embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than 85 Pa • s in a shear rate of 8.4 s⁻¹ after allowing to stand for 24 hours at 25°C ± 1°C.

2. The embedding resin according to claim 1, wherein the acid anhydride curing agent has a viscosity at 25°C ± 1°C of not higher than 170 mPa • s.

3. The embedding resin according to claim 1, which contains the filler in an amount of from 51% by weight to 74% by weight.

4. The embedding resin according to claim 1, wherein the filler contains at least one inorganic filler.

5. A wiring substrate comprising: an insulating substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin according to claim 1, wherein the at least one electronic part is embedded with the embedding resin.

6. A wiring substrate comprising: a core substrate;
and a build-up layer provided on at least one side of the core
substrate and formed by alternately laminating an insulating
layer and a wiring layer, wherein at least one of the core
5 substrate and the building-up layer has an opening
penetrating therethrough, and an electronic part is disposed
in the opening and embedded with an embedding resin according
to claim 1.